

Solid State Devices, Inc.

14830 Valley View Blvd * La Mirada, Ca 90638

Phone: (562) 404-7855 * Fax: (562) 404-1773

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DESIGNER'S DATA SHEET

Part Number / Ordering Information ^{1/}

SFF11N80

- Screening ^{2/} = Not Screen
 TX = TX Level
 TXV = TXV Level
 S = S Level
- Lead Option ^{3/} = Straight Leads
 DB = Down Bend
 UB = Up Bend
- Package ^{3/} M = TO-254
 Z = TO-254Z

SFF11N80 Series

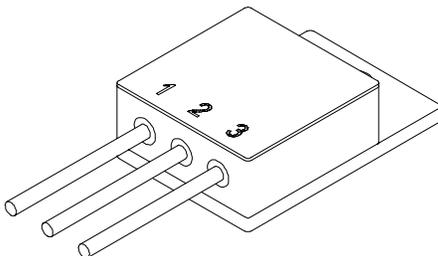
**11 AMP / 800 Volts
 0.95 Ω
 N-Channel MOSFET**

Features:

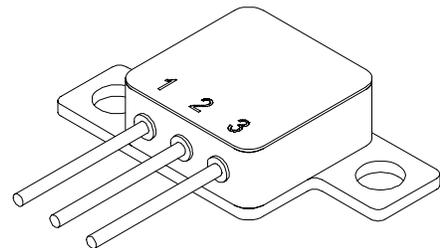
- Rugged Construction with Polysilicon Gate Cell
- Low R_{DS(ON)} and High Transconductance
- Excellent High Temperature Stability
- Very Fast Switching Speed
- Fast Recovery and Superior dV/dt performance
- Increased Reverse Energy Capability
- Low Input and Transfer Capacitance for Easy Paralleling
- Hermetically Sealed, Isolated Package
- Ceramic Seal Package Available. Contact Factory
- TX, TXV, S-Level screening available
- Replacement for IXTH11N80 Types

Maximum Ratings	Symbol	Value	Units
Drain – Source Voltage	V _{DS}	800	Volts
Gate – Source Voltage	V _{GS}	±20	Volts
Continues Collector Current	I _D	11	Amps
Power Dissipation	P _D	150 114	W
Operating & Storage Temperature	Top & Tstg	-55 to +175	°C
Maximum Thermal Resistance Junction to Case	R _{θJC}	0.83	°C/W

TO-254 (M)



TO-254Z (Z)



NOTE: All specifications are subject to change without notification.
 SCD's for these devices should be reviewed by SSDI prior to release.

DATA SHEET #: F00213C

DOC



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SFF11N80 Series

Electrical Characteristics ^{4/}	Symbol	Min	Typ	Max	Units	
Drain to Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250\mu A$)	BV_{DSS}	800	—	—	Volts	
Drain to Source On State Resistance ($V_{GS} = 10V, I_D = 5.5A$)	$R_{DS(on)}$	—	—	0.95	Ω	
On State Drain Current ($V_{DS} > I_{D(on)} \times R_{DS(on)} \text{ Max}, V_{GS} = 10V$)	$I_{D(on)}$	11	—	—	A	
Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 250\mu A$)	$V_{GS(th)}$	2.0	—	4.5	V	
Gate to Source Leakage ($V_{GS} = \pm 20V$)	I_{GSS}	—	—	± 100	nA	
Zero Gate Voltage Drain Current ($V_{GS} = 0V$)	I_{DSS}	—	—	250 1.0	μA mA	
Forward Transconductance * ($V_{DS} > I_{D(on)} \times R_{DS(on)} \text{ Max}, I_D = 5.5A$)	g_{fs}	8.0	14	—	Mho	
Total Gate Charge	Q_g	—	128	145	nC	
Gate to Source Charge	Q_{gs}	—	30	55		
Gate to Drain Charge	Q_{gd}	—	55	80		
Turn on Delay Time	$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10V$ $V_{DS} = 640V$ $I_D = 5.5A$ $R_G = 2.0\Omega$	—	20	50	nsec
Rise Time			—	33	50	
Turn on Delay Time			—	63	100	
Fall Time			—	32	50	
Diode Forward Voltage * ($I_F = 11A, V_{GS} = 0V$)	V_{SD}	—	—	1.5	V	
Diode Reverse Recovery Time ($I_F = 11A, di/dt = 100A/\mu sec$)	t_{rr}	—	—	550	nsec	
Input Capacitance	C_{iss} C_{oss} C_{rss}	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1MHz$	—	4200	—	pF
Output Capacitance			—	360	—	
Reverse Transfer Capacitance			—	100	—	

NOTES:

* Pulse Test: Pulse Width = 300 μsec , Duty Cycle = 2%

1/ For Ordering Information, Price, and Availability Contact Factory.

2/ Screening per MIL-PRF-19500

3/ For Package Outlines Contact Factory.

4/ Unless Otherwise Specified, All Electrical Characteristics @25°C.

Available Part Numbers:

SFF11N80M; SFF11N80MDB; SFF11N80MUB;
SFF11N80Z; SFF11N80ZDB; SFF11N80ZUB;

PIN ASSIGNMENT (Standard)

Package	Drain	Source	Gate
TO-254 (M)	Pin 1	Pin 2	Pin 3
TO-254Z (Z)	Pin 1	Pin 2	Pin 3

